

Loctite® 3532 High viscosity Dam Encapsulant

Category : Polymer , Adhesive , Thermoset

Material Notes:

COB/DCA Encapsulants are essential to the reliability of flip chip assemblies because they minimize the thermal mismatch between the flip chip and substrate. Loctite® Underfills and Encapsulants improve assembly operations by providing superior reliability and faster throughput. Improved reliability is achieved through products that have a high Tg, low CTE, high throughput and excellent adhesion. Faster throughput and higher yields are achieved through faster flow characteristics and increased cure speeds. Loctite® 3532 High viscosity Dam Encapsulant Utilized in applications where COB density favors square or rectangular footprints, or where potting wells or indentations are not provided. "Dam" material controls flow of liquid encapsulant.

Order this product through the following link:

http://www.lookpolymers.com/polymer_Loctite-3532-High-viscosity-Dam-Encapsulant.php

Physical Properties	Metric	English	Comments
Density	1.76 g/cc	0.0636 lb/in ³	
Viscosity	250000 cP	250000 cP	Haake cone and plate rheometer @ 5/sec (35mm/2° cone)

Thermal Properties	Metric	English	Comments
CTE, linear	19.0 µm/m-°C	10.6 µin/in-°F	
	@Temperature 20.0 °C	@Temperature 68.0 °F	
Glass Transition Temp, Tg	155 °C	311 °F	

Electrical Properties	Metric	English	Comments
Volume Resistivity	3.10e+15 ohm-cm	3.10e+15 ohm-cm	
Surface Resistance	2.40e+16 ohm	2.40e+16 ohm	

Processing Properties	Metric	English	Comments
Cure Time	30.0 min	0.500 hour	Full Cure
	@Temperature 150 °C	@Temperature 302 °F	
Shelf Life	3.00 Month	3.00 Month	
	@Temperature -40.0 °C	@Temperature -40.0 °F	

Descriptive Properties	Value	Comments
Color	Black	

Contact Songhan Plastic Technology Co.,Ltd.

Website : www.lookpolymers.com

Email : sales@lookpolymers.com

Tel : +86 021-51131842

Mobile : +86 13061808058

Skype : lookpolymers

Address : United North Road 215,Fengxian District, Shanghai City,China